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TFT | CHARACTER | UWVD | FSC | SEGMENT | CUSTOM | REPLACEMENT

## TFT Display Module

Part Number  
E28RA-I-CW480-N

### Overview:

- 2.8-inch TFT (50.5x69.7')
- 240 x 320
- 16.7M Color
- 1.8" @ 1000x600
- 8/9/16/18-bit MCU Interface
- 3/4-wire SPI Interface
- All View
- Transmissive, IPS
- Wide Temperature
- No Touch Panel
- 480 nits
- TFT IC: ST7789V
- RoHS Compliant



## Description

This is a color active matrix TFT (Thin Film Transistor) LCD (Liquid Crystal Display) that uses amorphous silicon TFT as a switching device. This model is composed of a transmissive type TFT LCD Panel, driver circuit and a backlight unit. The resolution of the 2.8" TFT LCD contains 240(RGB)x320 pixels and can display up to 262k colors.

## TFT Features

Low Input Voltage: 3.3V

Display Colors: 65k/262k

Interface: 8/9/16/18-bit MCU

16/18-bit RGB

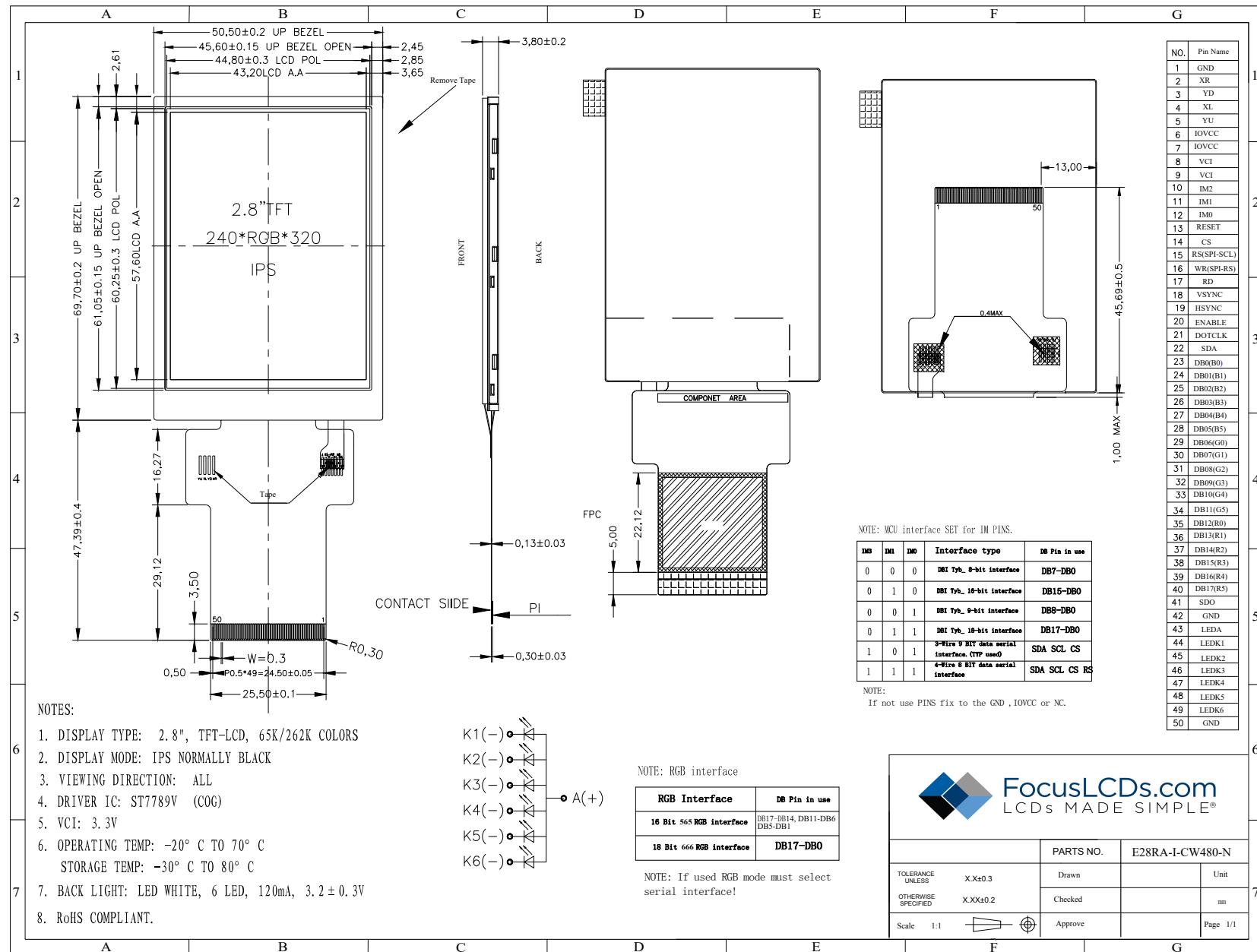
3/4-wire Serial

General Information Items	Specification	Unit	Note
	Main Panel		
TFT Display area (AA)	43.20(H) x 57.60(V) (2.8 inch)	mm	-
Driver Element	TFT active matrix	-	-
Display Colors	65k/262k	colors	-
Number of pixels	240(RGB)x320	dots	-
TFT Pixel arrangement	RGB vertical stripe	-	-
Pixel Pitch	0.18 (H)x0.18(V)	mm	-
Viewing angle	ALL	o'clock	-
TFT Controller IC	ST7789V	-	-
TFT Interface	MCU, RGB, SPI	-	-
Display mode	Transmissive/ Normally Black	-	-
Operating temperature	-20~+70	°C	-
Storage temperature	-30~+80	°C	-

## Mechanical Information

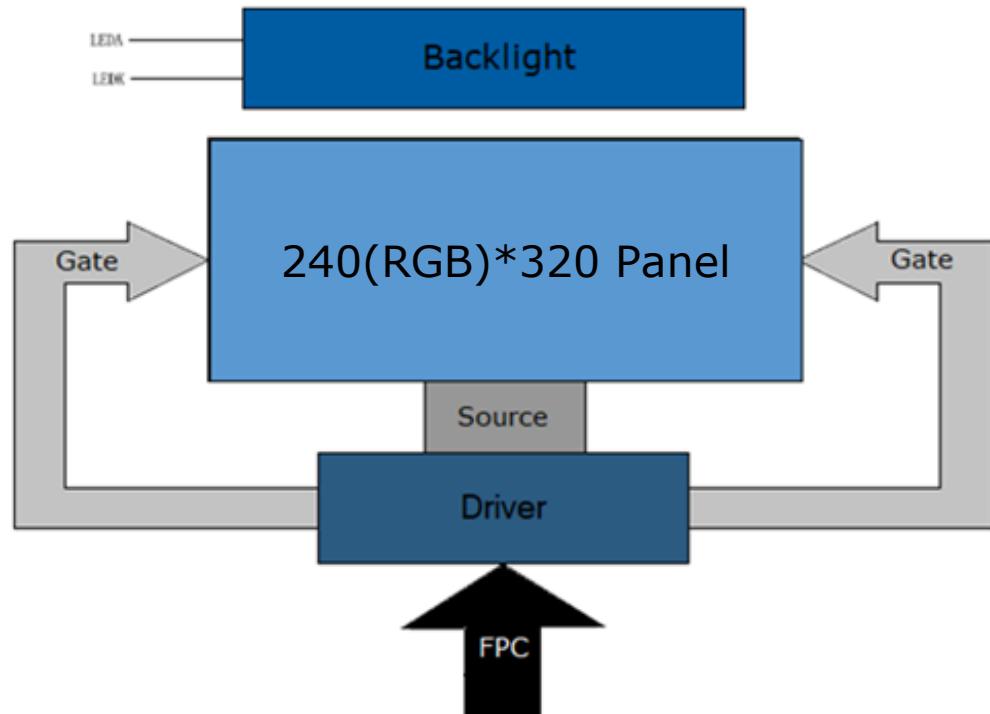
Item	Min	Typ.	Max	Unit	Note
Module Size	Horizontal (H)	50.50		mm	-
	Vertical (V)	69.70		mm	-
	Depth (D)	2.60		mm	-
	Weight	TBD		g	

# 1. Outline Dimensions





## 2. Block Diagram





### 3. Input Terminal Pin Assignment

Recommended Connector: FH12S-50S-0.5SH(55)

NO.	Symbol	Description				I/O
1	GND	Ground				P
2	XR (NC)	Touch panel right glass terminal				A/D
3	YD (NC)	Touch panel bottom film terminal				A/D
4	XL (NC)	Touch panel left glass terminal				A/D
5	YU (NC)	Touch panel top film terminal				A/D
6	IOVCC	Supply voltage (1.65-3.3V)				P
7	IOVCC	Supply voltage (1.65-3.3V)				P
8	VCI	Supply voltage (3.3V)				P
9	VCI	Supply voltage (3.3V)				P
10-12	IM3 IM2 IM0	Interface selection	IM3	IM2	IM0	Pins used
		DBI 8-bit	0	0	0	DB7-DB0
		DBI 16-bit	0	1	0	DB15-DB0
		DBI 9-bit	0	0	1	DB8-DB0
		DBI 18-bit	0	1	1	DB17-DB0
		3-wire, 9-bit SPI	1	0	1	SDA SCL CS
		4-wire, 8-bit SPI	1	1	1	SDA SCL CS RS
13	RESET	Reset signal of the device. Must be applied to properly initialize the device. Signal is active low.				I
14	CS	Chip select pin. When not used this pin can be fixed low.				I
15	RS(SPI_SCL)	Data or command signal for the parallel MCU interface. RS=1: data is selected, RS=0: command is selected. The clock for the serial interface. If not used, pin to VCI or GND.				I
16	WR(SPI_RS)	Write signal in the parallel MCU interface. Command or parameter select signal for the 4-wire serial interface. If not used, pin to VCI or GND.				I
17	RD	Read signal for the MCU parallel interface. If not used, pin to VCI or GND.				O
18	VSYNC	Frame synchronizing signal for the RGB interface. If not used, pin to VCI or GND.				I
19	HSYNC	Line synchronizing signal for the RGB interface. If not used, pin to VCI or GND.				I
20	ENABLE	Data enable signal for the RGB interface. If not used, pin to VCI or GND.				I
21	DOTCLK	Dot clock signal for the RGB interface. If not used, pin to VCI or GND.				I
22	SDA	Serial input signal. The data is applied at the rising edge of the SCL signal. If not used, pin to VCI or GND.				I
23-40	DB0-DB17	18-bit parallel bi-directional data bus for the RGB and MCU interfaces. Fix to GND when not used.				I/O
41	SDO	Serial data output for the SPI interface.				I
42	GND	Ground				P
43	LEDA	Anode pin of the backlight				P
44	LEDK1	Cathode pin of the backlight				P
45	LEDK2	Cathode pin of the backlight				P
46	LEDK3	Cathode pin of the backlight				P
47	LEDK4	Cathode pin of the backlight				P
48	LEDK5	Cathode pin of the backlight				P
49	LEDK6	Cathode pin of the backlight				P
50	GND	Cathode pin of the backlight				P

I: Input, O: Output, P: Power



## 4. LCD Optical Characteristics

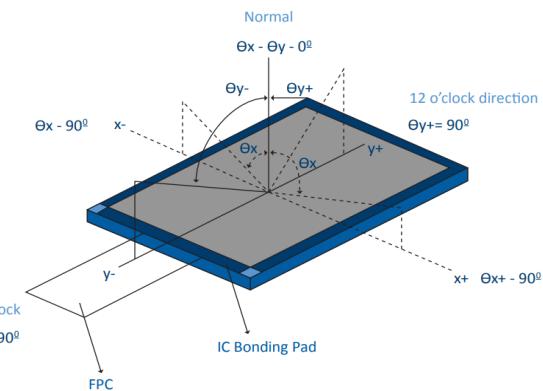
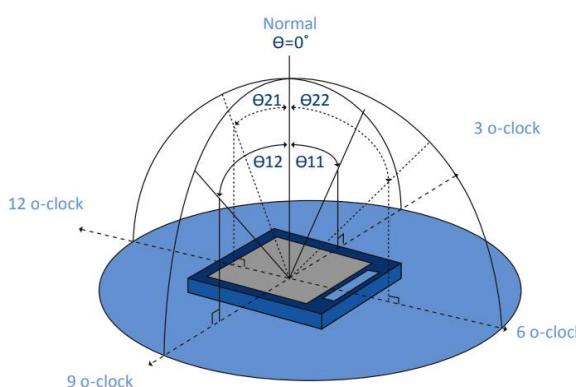
### 4.1 Optical Specifications

Item		Symbol	Condition	Min	Typ.	Max	Unit	Note	
Color Gamut		S%	θ=0 Normal viewing angle	--	60	--	%	(3)	
Contrast Ratio		CR		600	800	--	%	(2)	
Response Time	Rising	TR+TF		--	30	40	ms	(4)	
	Falling			0.288	0.308	0.328			
Color Filter Chromaticity	White	W <sub>X</sub>		0.310	0.330	0.350	(5)(6)		
		W <sub>Y</sub>		0.621	0.641	0.661			
	Red	R <sub>X</sub>		0.317	0.337	0.357			
		R <sub>Y</sub>		0.254	0.274	0.294			
	Green	G <sub>X</sub>		0.540	0.560	0.580			
		G <sub>Y</sub>		0.121	0.141	0.161			
	Blue	B <sub>X</sub>		0.093	0.113	0.133			
		B <sub>Y</sub>		--	80	--	degrees	(1)(6)	
Viewing Angle		ΘL	CR≥10	--	80	--			
		ΘR		--	80	--			
		ΘT		--	80	--			
		ΘB		--	80	--			
Option View Direction		ALL						(1)	



### Optical Specification Reference Notes:

(1) Definition of Viewing Angle: The viewing angle is the angle at which the contrast ratio is greater than 10. The viewing angles are determined for the horizontal or 3,9 o'clock direction and the vertical or 6,12 o'clock direction with respect to the optical axis which is normal to the LCD surface.

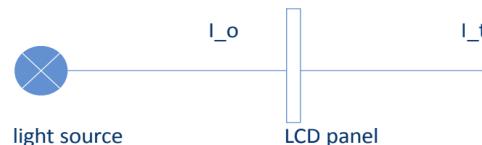


(2) Definition of Contrast Ratio (Cr): measured at the center point of panel. The contrast ratio (Cr) measured on a module, is the ratio between the luminance (Lw) in a full white area (R=G=B=1) and the luminance (Ld) in a dark area (R=G=B=0).

$$Cr = \frac{Lw}{Ld}$$

(3) Definition of transmittance (T%): The transmittance of the panel including the polarizers is measured with electrical driving. The equation for transmittance Tr is:

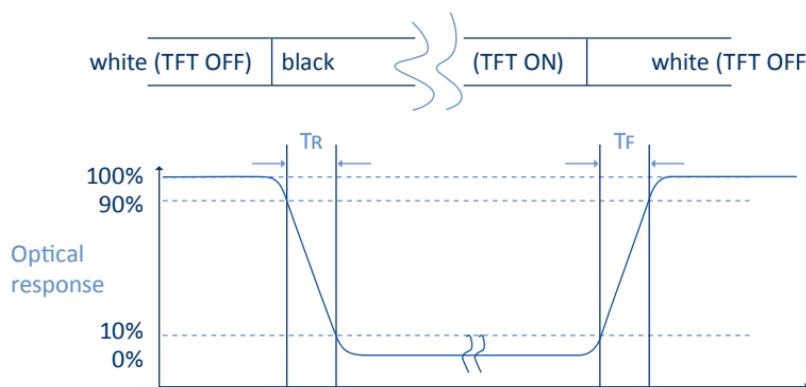
$$Tr = \frac{I_t}{I_o} \times 100\%$$



I<sub>o</sub> = the brightness of the light source.

I<sub>t</sub> = the brightness after panel transmission

(4) Definition of Response Time (Tr, Tf): The rise time 'Tr' is defined as the time for luminance to change from 90% to 10% as a result of a change of the electrical condition. The fall time 'Tf' is defined as the time for luminance to change from 10% to 90% as a result of a change of the electrical condition.



### (5) Definition of Color Gamut:

Measuring machine CFT-01. NTSC's Primaries:

$R(x,y,Y), G(x,y,Y), B(x,y,Y)$ . FPM520 of Westar Display Technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics. The color chromaticity shall be calculated from the spectral data measured with all pixels first in red, green, blue and white. Measurements shall be made at the center of the panel.

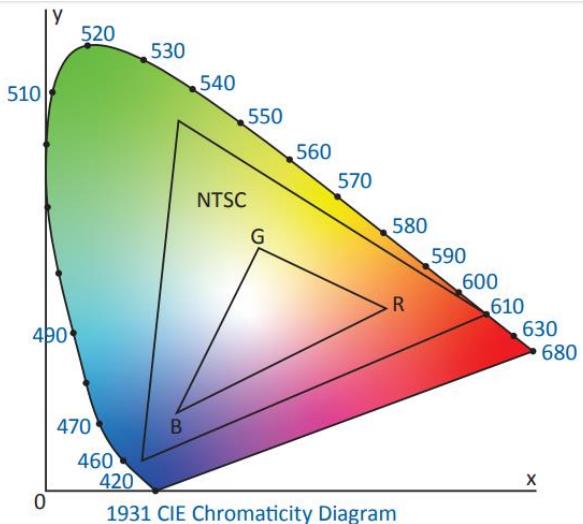
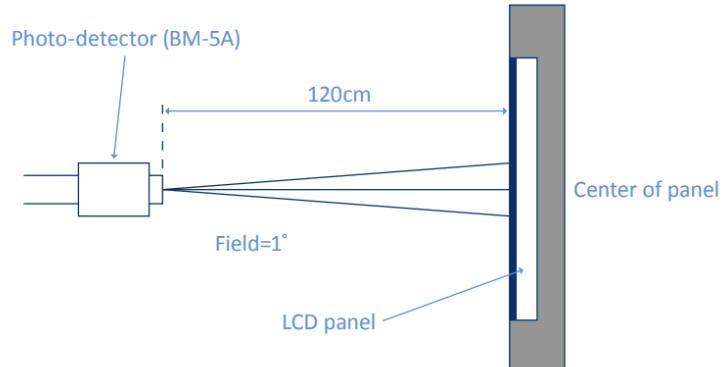
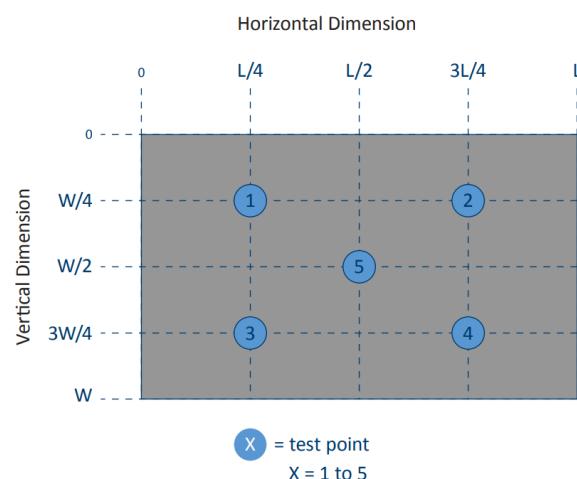
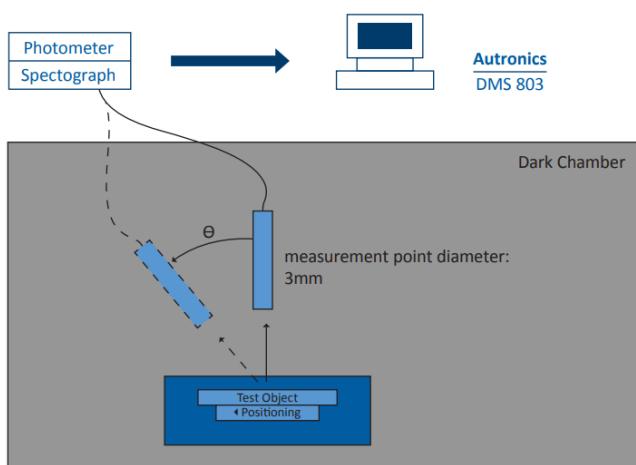


Fig. 1931 CIE chromacity diagram

$$\text{Color gamut: } S = \frac{\text{Area of RGB triangle}}{\text{Area of NTSC triangle}} \times 100\%$$

### (6) Definition of Optical Measurement Setup:

The LCD module should be stabilized at a given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 20 minutes.





## 5. TFT Electrical Characteristics

### 5.1 Absolute Maximum Rating (Ta=25 °C, VSS=0V)

Characteristics	Symbol	Min	Max	Unit
Digital Supply Voltage	VDD	-0.3	4.6	V
Digital Interface Supply Voltage	IOVCC	-0.3	4.6	
Operating Temperature	TOP	-20	+70	°C
Storage Temperature	TST	-30	+80	°C

*NOTE: If the absolute maximum rating of the above parameters is exceeded, even momentarily, the quality of the product may be degraded. Absolute maximum ratings specify the values which the product may be physically damaged if exceeded. Be sure to use the product within the range of the absolute maximum ratings.*

### 5.2 DC Electrical Characteristics

Characteristics	Symbol	Min	Typ.	Max	Unit	Note
Digital Supply Voltage	VCI	2.5	3.3	4.2	V	
Digital Interface Supply Voltage	IOVCC	1.65	3.3	4.2	V	
Normal Mode Current	IDD	--	8	--	mA	
Level Input Voltage	VIH	0.7IOVCC	--	IOVCC	V	
	VIL	GND	--	0.3IOVCC	V	
Level Output Voltage	VOH	0.8IOVCC	--	IOVCC	V	
	VOL	GND	--	0.2IOVCC	V	

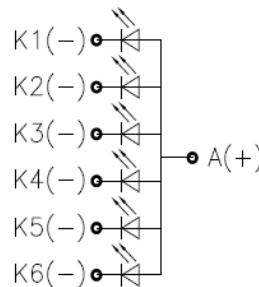
### 5.3 LED Backlight Characteristics

Item	Symbol	Min	Typ.	Max	Unit	Note
Forward Current	IF	90	120	--	mA	
Forward Voltage	VF	--	3.2	--	V	
LCM Luminance	LV	430	480	--	cd/m <sup>2</sup>	Note 3
LED lifetime	Hr	--	50000	--	hour	Note 1 & 2
Uniformity	AVg	80	--	--	%	Note 3

The back-light system is edge-lighting type with 6 white LEDs.

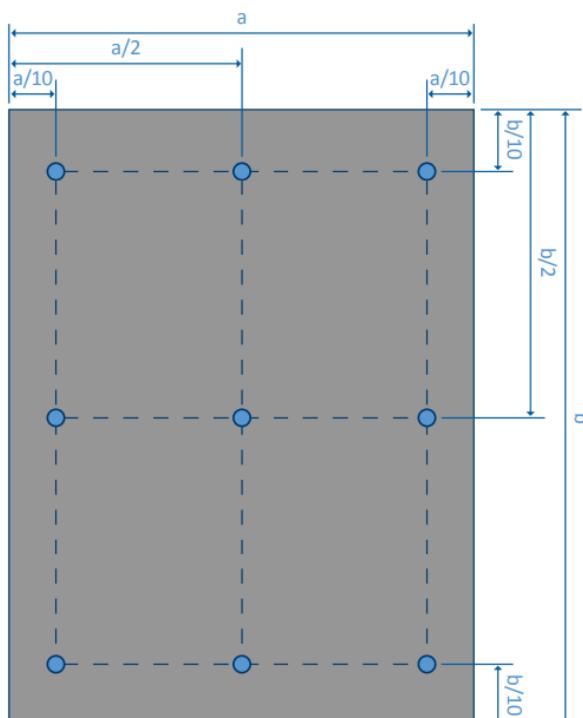
Note 1: LED lifetime (Hr) can be defined as the time in which it continues to operate under the condition:  $T_a=25\pm3\text{ }^{\circ}\text{C}$ , typical IL value indicated in the above table until the brightness becomes less than 50%.

Note 2: The “LED lifetime” is defined as the module brightness decrease to 50% original brightness at  $T_a=25^{\circ}\text{C}$  and  $IL=120\text{mA}$ . The LED lifetime could be decreased if operating IL is larger than 120mA. The constant current driving method is suggested.



Backlight LED Circuit

Note 3: Luminance Uniformity of these 9 points is defined as below:



$$\text{Luminance} = \frac{\text{Total Luminance of 9 points}}{9}$$

$$\text{Uniformity} = \frac{\text{minimum luminance in 9 points(1-9)}}{\text{maximum luminance in 9 points(1-9)}}$$

## 6. AC Characteristic

### 6.1 Parallel RGB Interface Characteristics

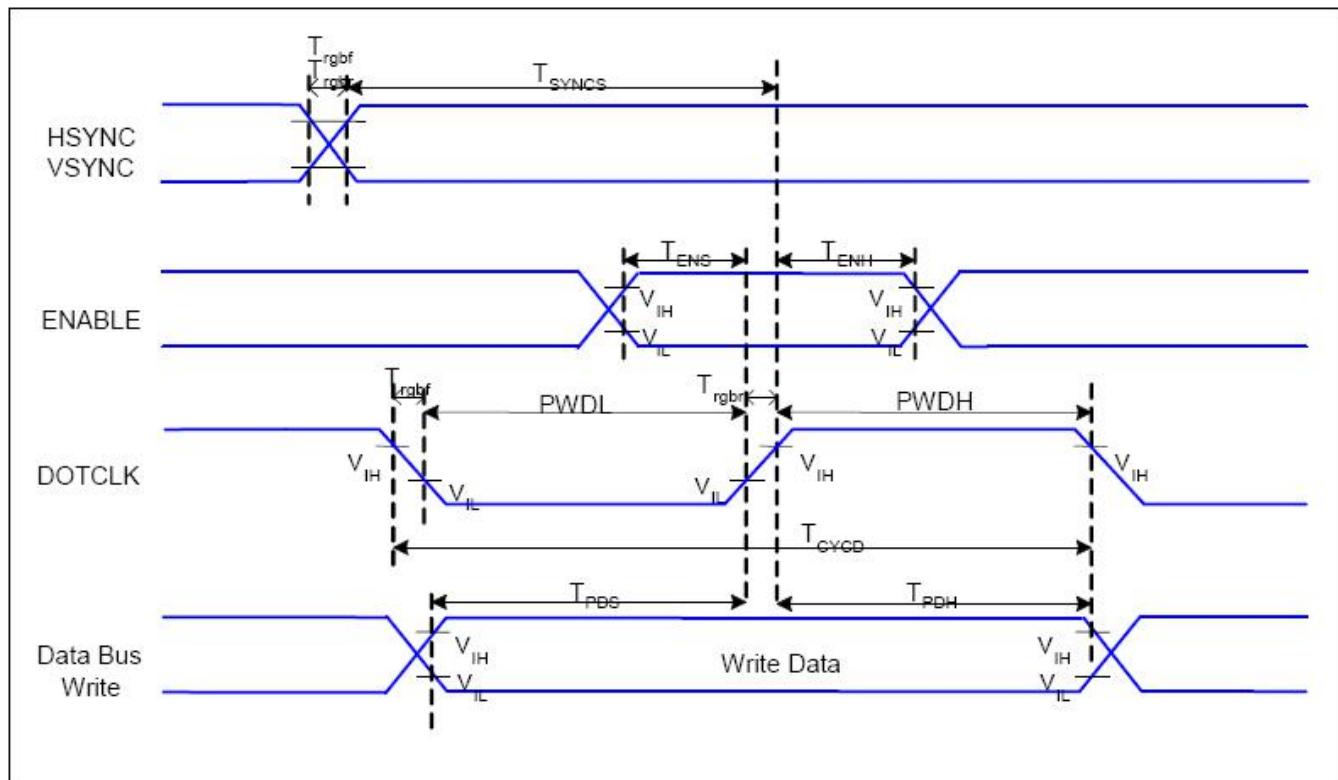


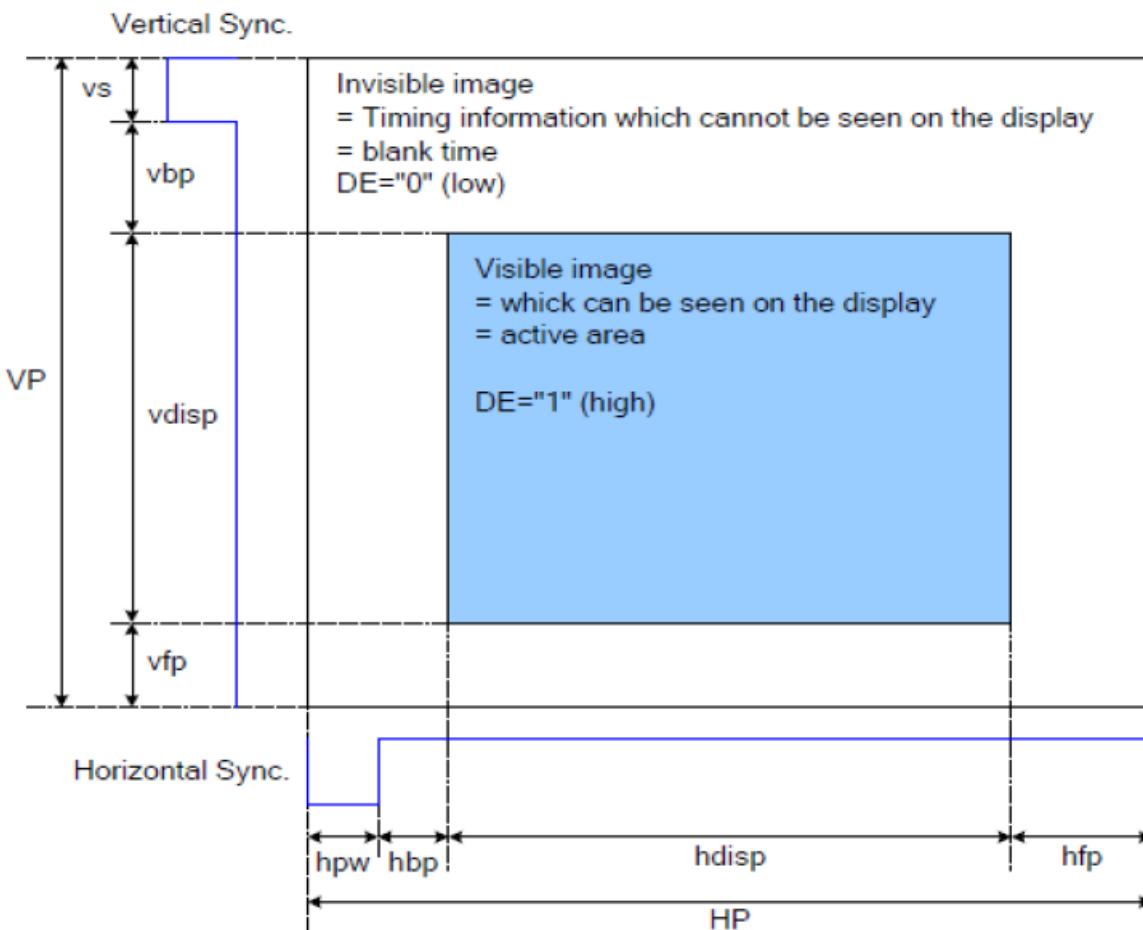
Figure 6.1: Parallel RGB Interface Timing Diagram

Signal	Symbol	Parameter	Min	Max	Unit	Description
HSYNC, VSYNC	$T_{SYNCs}$	VSYNC, HSYNC Setup Time	30	-	ns	
ENABLE	$T_{ENS}$	Enable Setup Time	25	-	ns	
	$T_{ENH}$	Enable Hold Time	25	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	60	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	60	-	ns	
	$T_{CYCD}$	DOTCLK Cycle Time	120	-	ns	
	$T_{RGHR}, T_{RGHF}$	DOTCLK Rise/Fall Time	-	20	ns	
DB	$T_{DBS}$	DB Data Setup Time	50	-	ns	
	$T_{DBH}$	DB Data Hold Time	50	-	ns	

Table 6.1: Parallel RGB Interface Timing Characteristics

## 6.2 Timing Tables

The display operation via the RGB interface is synchronized with the VSYNC, HSYNC and DOTCLK signals. The data can be written only within the specified area with low power consumption by using the window address function. The back porch and front porch are used to set the RGB interface timing signals.



Parameter	Symbol	Min	Typ	Max		Unit
DCLK cycle time	dclk	120	-	--		ns
Horizontal sync width	hpw	2	10	16		dclk
Horizontal back porch	hbp	2	20	24		dclk
Horizontal front porch	hfp	2	10	16		dclk
Vertical sync width	vs	1	2	4		Line
Vertical back porch	vbp	1	2	--		Line
Vertical front porch	vfp	3	4	--		Line

Table 6.2: RGB Interface Timing Table

### 6.3 Display Serial Interface Characteristics (3-line SPI system)

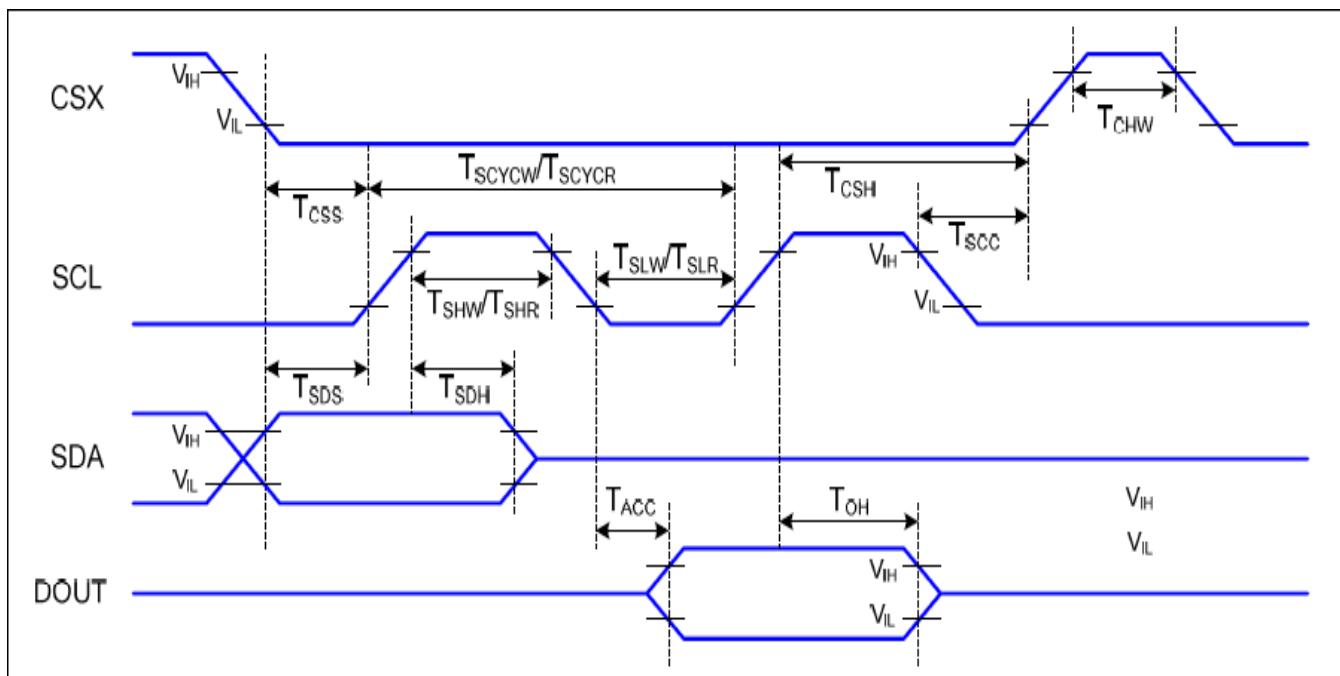


Figure 6.3: Serial Interface 3-SPI Timing Diagram

$VDDI = 1.64$  to  $3.3V$ ,  $VDD = 2.4$  to  $3.3V$ ,  $AGND=DGND=0V$ ,  $Ta=-30$  to  $70$   $C^\circ$

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	$T_{CSS}$	Chip select setup time (write)	15		ns	
	$T_{CSH}$	Chip select hold time (write)	15		ns	
	$T_{CSS}$	Chip select setup time (read)	60		ns	
	$T_{SCC}$	Chip select hold time (read)	65		ns	
	$T_{CHW}$	Chip select "H" pulse width	40		ns	
SCL	$T_{SCYCW}$	Serial clock cycle (write)	66		ns	
	$T_{SHW}$	SCL "H" pulse width (write)	15		ns	
	$T_{SLW}$	SCL "L" width (write)	15		ns	
	$T_{SCYCR}$	Serial clock cycle (read)	150		ns	
	$T_{SHR}$	SCL "H" pulse width (read)	60		ns	
	$T_{SLR}$	SCL "L" pulse width (read)	60		ns	
SDA (DIN)	$T_{SDS}$	Data setup time	30		ns	
	$T_{SDH}$	Data hold time	30			
SDA (DOUT)	$T_{ACC}$	Access time	10	50	ns	For max CL=30pF
	$T_{OH}$	Output disable time	15	50		For min CL=8pF

Table 6.3: 3-line Serial Interface Timing Characteristics

Note: The rising time and falling time ( $T_r$ ,  $T_f$ ) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of  $VDDI$  for Input signals

## 6.4 Display Serial Interface Characteristics (4-line SPI serial)

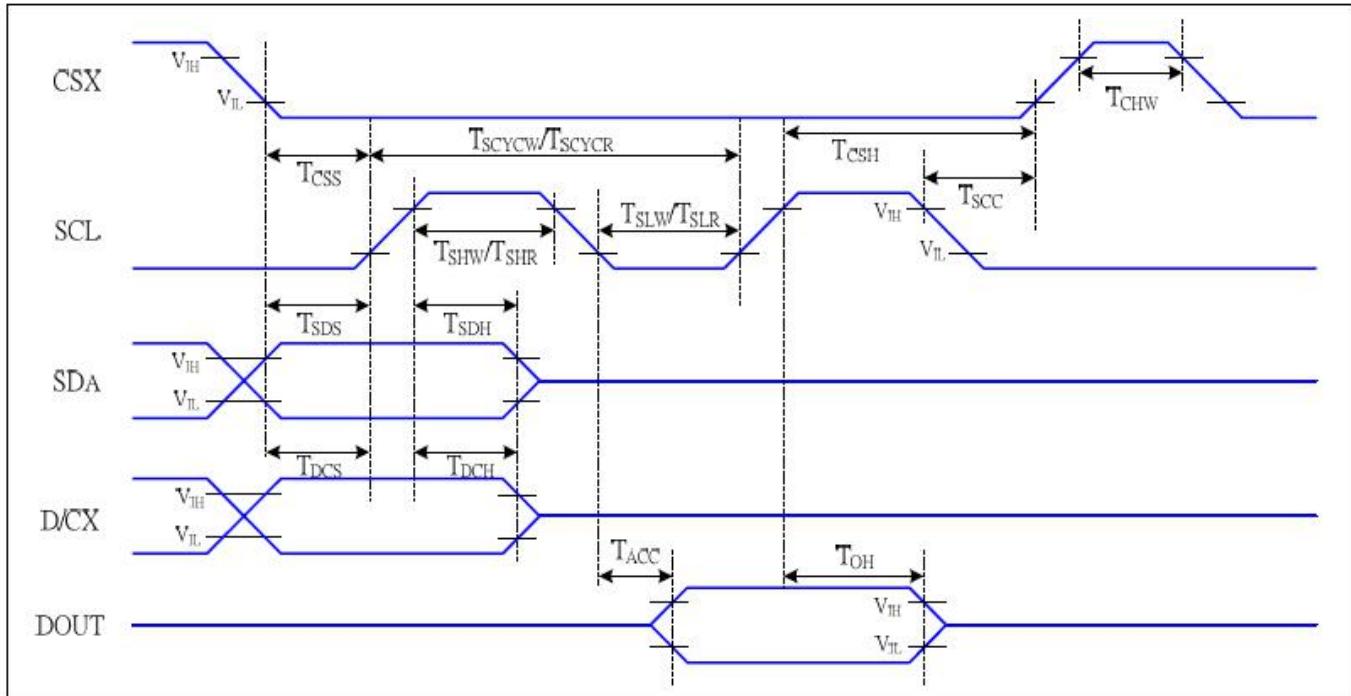


Figure 6.4: Serial Interface 4-SPI Timing Diagram

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T <sub>CS</sub>	Chip select setup time (write)	15		ns	
	T <sub>CSH</sub>	Chip select hold time (write)	15		ns	
	T <sub>CS</sub>	Chip select setup time (read)	60		ns	
	T <sub>SCC</sub>	Chip select hold time (read)	65		ns	
	T <sub>CHW</sub>	Chip select "H" pulse width	40		ns	
SCL	T <sub>SCYCW</sub>	Serial clock cycle (write)	66		ns	write command & data ram
	T <sub>SHW</sub>	SCL "H" pulse width (write)	15		ns	
	T <sub>SLW</sub>	SCL "L" width (write)	15		ns	
	T <sub>SCYCR</sub>	Serial clock cycle (read)	150		ns	
	T <sub>SHR</sub>	SCL "H" pulse width (read)	60		ns	
	T <sub>SLR</sub>	SCL "L" pulse width (read)	60		ns	
D/CX	T <sub>DGS</sub>	D/CX setup time	10		ns	
	T <sub>DCH</sub>	D/CX hold time	10		ns	
SDA (DIN)	T <sub>SDS</sub>	Data setup time	10		ns	
	T <sub>SDH</sub>	Data hold time	10		ns	
DOUT	T <sub>ACC</sub>	Access time	10	50	ns	For max CL=30pF For min CL=8pF
	T <sub>OH</sub>	Output disable time	15	50	ns	

Table 6.5: 4-line Serial Interface Timing Characteristics

For max CL=30pF For min CL=8pF

Note: The rising time and falling time ( $T_r$ ,  $T_f$ ) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

## 6.5 8080 Series MCU Parallel Interface Characteristics: 18/16/9/8-bit Bus

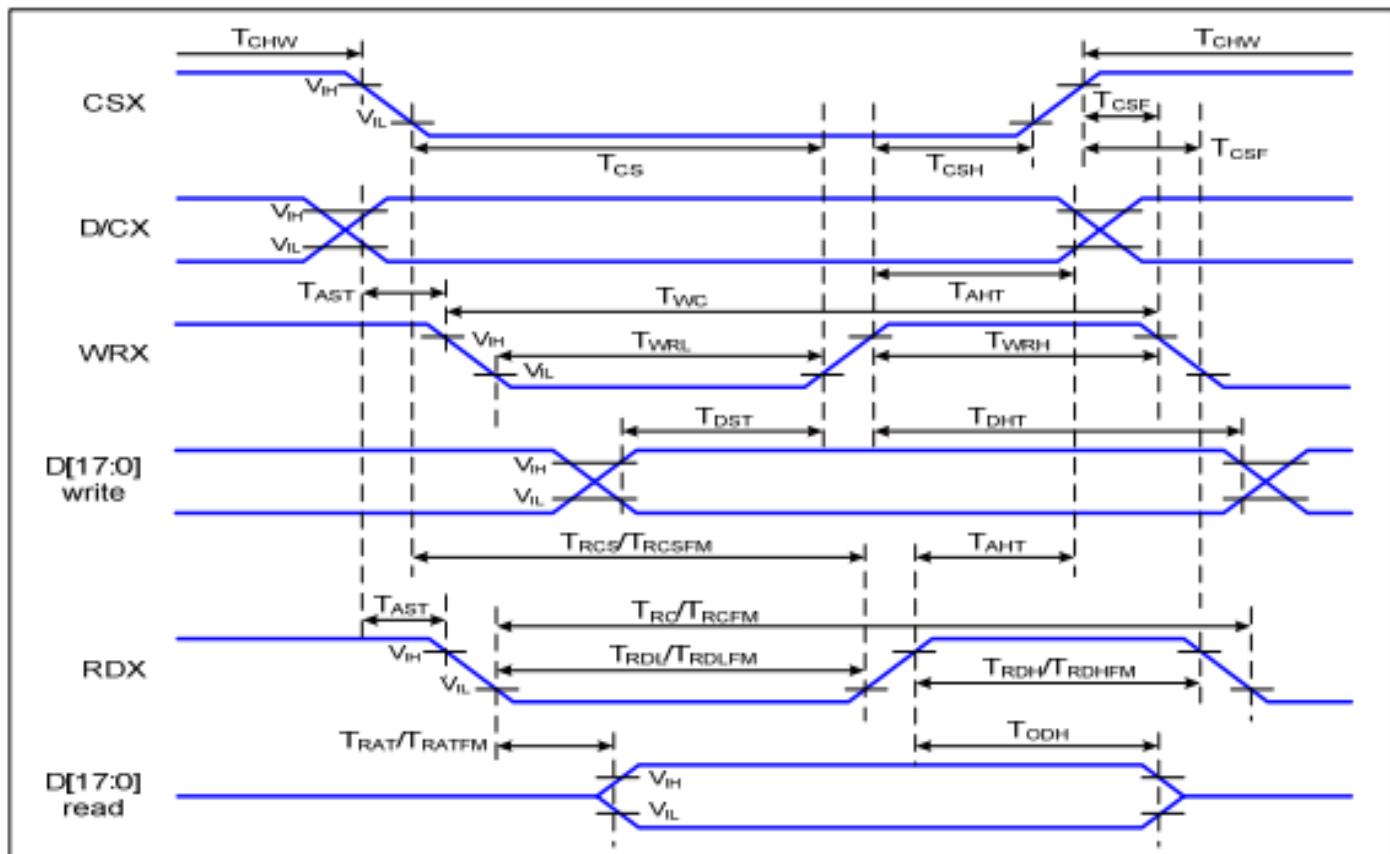


Figure 6.5: Parallel Interface Timing Characteristics (8080-Series MCU Interface)

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	$T_{AST}$	Address setup time	0	-	ns	
	$T_{AHT}$	Address hold time (Write/Read)	10	-	ns	
CSX	$T_{CHW}$	Chip select "H" pulse width	0	-	ns	
	$T_{CS}$	Chip select setup time (Write)	15	-	ns	
	$T_{RCS}$	Chip select setup time (Read ID)	45	-	ns	
	$T_{RCSFM}$	Chip select setup time (Read FM)	355	-	ns	
	$T_{CSF}$	Chip select wait time (Write/Read)	10	-	ns	
	$T_{CSH}$	Chip select hold time	10	-	ns	
WRX	$T_{WC}$	Write cycle	66	-	ns	
	$T_{WRH}$	Control pulse "H" duration	15	-	ns	
	$T_{WRL}$	Control pulse "L" duration	15	-	ns	
RDX (ID)	$T_{RC}$	Read cycle (ID)	160	-	ns	
	$T_{RDH}$	Control pulse "H" duration (ID)	90	-	ns	
	$T_{RDL}$	Control pulse "L" duration	45	-	ns	
RDX (FM)	$T_{RCFM}$	Read cycle (FM)	450	-	ns	
	$T_{RDHFM}$	Control pulse "H" duration (FM)	90	-	ns	
	$T_{RDLFM}$	Control pulse "L" duration (FM)	355	-	ns	
D[17:0], D[15:0], D[8:0], D[7:0]	$T_{DST}$	Write data setup time	10	-	ns	For max CL=30pF For min CL=8pF
	$T_{DHT}$	Write data hold time	10	-	ns	
	$T_{RAT}$	Read access time (ID)	-	40	ns	
	$T_{RATFM}$	Read access time (FM)	-	340	ns	
	$T_{ROD}$	Output disable time	20	80	ns	

Table 6.5: 8080 Series MCU Parallel Timing Characteristics

### 6.3 Reset Timing

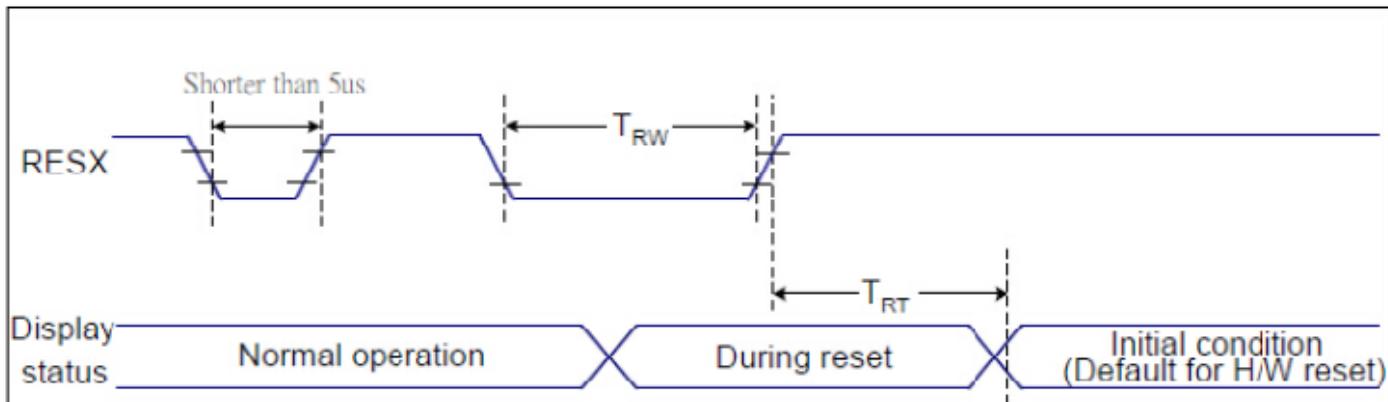


Figure 6.6: Reset Timing Diagram

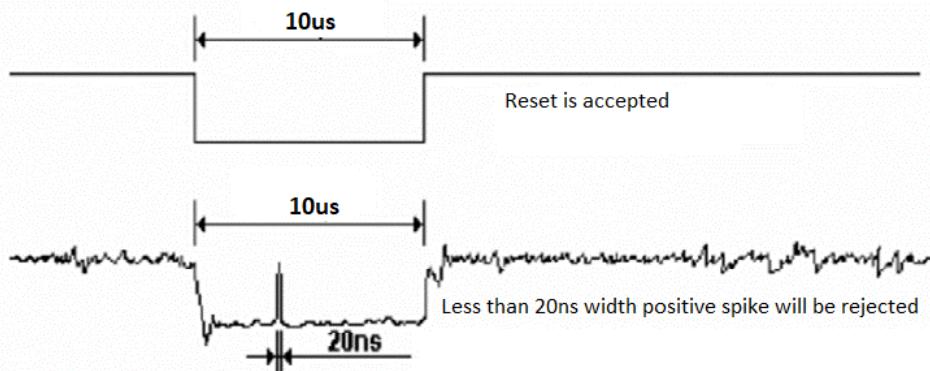
Related Pins	Symbol	Parameter	Min	Max	Unit
RESX	$T_{RW}$	Reset pulse duration	10	-	us
	$T_{RT}$	Reset cancel	-	5 (Note 1,5) 120 (Note 1, 6, 7)	ms

Notes:

1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time ( $t_{RT}$ ) within 5ms after a rising edge of RESX.
2. Spike due to an electrostatic discharge on RESX line does not because irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9 us	Reset starts

3. During the resetting period, the display will be blanked (the display is entering blanking sequence, which maximum time is 120ms, when reset starts in Sleep Out mode. The display remains the blank state in Sleep in mode) and then return to Default condition for Hardware Reset.
4. Spike Rejection also applies during a valid reset pulse as shown below:



5. When Reset applied during Sleep In Mode.
6. When Reset applied during Sleep Out Mode.
7. It is necessary to wait 5ms after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120ms.



## 7. Cautions and Handling Precautions

### 7.1 Handling and Operating the Module

1. When the module is assembled, it should be attached to the system firmly. Do not warp or twist the module during assembly work.
2. Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
3. Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
4. Do not allow drops of water or chemicals to remain on the display surface. If you have the droplets for a long time, staining and discoloration may occur.
5. If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
6. The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane. Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
7. If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
8. Protect the module from static; it may cause damage to the CMOS ICs.
9. Use fingerstalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
10. Do not disassemble the module.
11. Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
12. Pins of I/F connector shall not be touched directly with bare hands.
13. Do not connect, disconnect the module in the “Power ON” condition.
14. Power supply should always be turned on/off by the item Power On Sequence & Power Off Sequence.

### 7.2 Storage and Transportation

1. Do not leave the panel in high temperature, and high humidity for a long time. It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%
2. Do not store the TFT-LCD module in direct sunlight.
3. The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
4. It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module. In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
5. This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.